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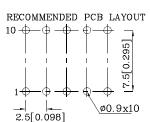
BAR GRAPH 5 SEGMENT

Features

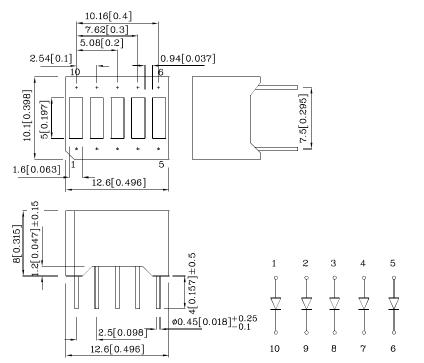
- Robust package
- ullet Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- \bullet Standard configuration: Gray face w/ white segments
- RoHS compliant







Package Schematics



Votes.

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P _D 62.5		mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Green (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_{R}	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

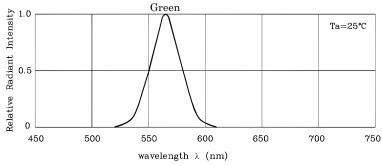
Part Number	Emitting Color	Emitting Material	Luminous Ir CIE127-2 (I _F =10mA	2007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XGUGX5D	Green	GaP	5600 1400*	11990 3990*	565*	5 Segment Bar graph-Display

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Oct 17.2016

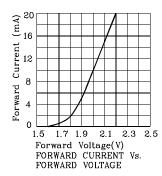


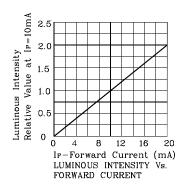


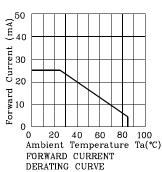


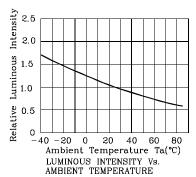
RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ Green

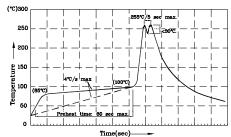








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:

 1. Recommend pre-heat temperature of 105°C or less (as m thermocouple attached to the LED pins) prior to immersion wave with a maximum solder bath temperature of 250°C.

 2. Peak wave soldering temperature between 245°C ~ 255°C.
- max).
 3.Do not apply stress to the epoxy resin while the temperature is a
 4.Fixtures should not incur stress on the component when mounting
 during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.
 7.During wave soldering, the PCB top-surface temperature should be
 kept below 105°C.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

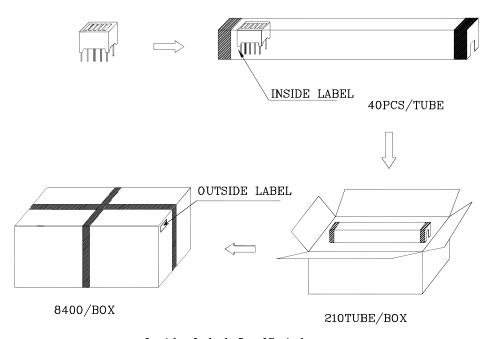
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

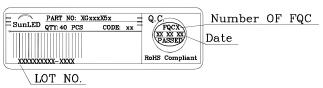




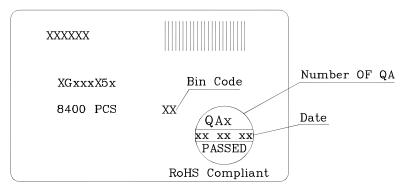
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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